

components may be inserted into the enclosure **15** as shown in FIG. **3** that create lateral keep-outs **175** and **180**. In order to accommodate the lateral keep-outs **175** and **180** in the modified enclosure **15** shown in FIG. **3**, the air mover **55** may be moved to the alternative position as shown. Other circumstances may involve the initial placement of the cooling system **40** in an enclosure **15** of one sort or another and thereafter the removal of the cooling system **40** and placement in another enclosure that has a different internal configuration. This may be a different computing device or just a different enclosure for the same computing device. In that circumstance, it may be appropriate to tailor the positioning of the air mover relative to the shroud in order to accommodate the internal workings of the new enclosure in which the cooling system is positioned. These represent just two examples of the advantages of using the disclosed modular embodiments.

[0031] While the invention may be susceptible to various modifications and alternative forms, specific embodiments have been shown by way of example in the drawings and have been described in detail herein. However, it should be understood that the invention is not intended to be limited to the particular forms disclosed. Rather, the invention is to cover all modifications, equivalents and alternatives falling within the spirit and scope of the invention as defined by the following appended claims.

What is claimed is:

1. A thermal management system, comprising:
a heat sink operable to convey heat from a heat generating component; and
a shroud having a first opening to direct air in a first direction past the heat sink and a second opening to direct air in a second direction past the heat sink.
2. The thermal management system of claim **1**, comprising an air mover coupled to the shroud in a first position to move air through the first opening or a second position to move air through the second opening.
3. The thermal management system of claim **1**, comprising a first removable cover over the first opening and a second removable cover over the second opening.
4. The thermal management system of claim **1**, wherein the heat sink includes a base member to thermally contact the heat generating component, the shroud being coupled to the base member.
5. The thermal management system of claim **1**, wherein the air mover comprises a fan or a blower.
6. The thermal management system of claim **1**, wherein the shroud comprises an integral structure.
7. The thermal management system of claim **1**, wherein the shroud comprises multiple components.
8. A computing device, comprising:
an enclosure;
a heat generating component in the enclosure;
a heat sink in the enclosure operable to convey heat from a heat generating component; and

a shroud in the enclosure and having a first opening to direct air in a first direction past the heat sink and a second opening to direct air in a second direction past the heat sink.

9. The computing device of claim **8**, comprising an air mover coupled to the shroud in a first position to move air through the first opening or a second position to move air through the second opening.

10. The computing device of claim **8**, comprising a first removable cover over the first opening and a second removable cover over the second opening.

11. The computing device of claim **8**, wherein the heat sink includes a base member to thermally contact the heat generating component, the shroud being coupled to the base member.

12. The computing device of claim **8**, wherein the air mover comprises a fan or a blower.

13. The computing device of claim **8**, wherein the shroud comprises an integral structure.

14. The computing device of claim **1**, wherein the shroud comprises multiple components.

15. A method of providing thermal management for a heat generating component, comprising:

placing a heat sink in thermal contact with the heat generating component;

coupling a shroud to the heat sink, the shroud having a first opening to direct air in a first direction past the heat sink and a second opening to direct air in a second direction past the heat sink; and

moving air through the first opening or the second opening.

16. The method of claim **15**, comprising coupling an air mover to the shroud in a first position to move air through the first opening or a second position to move air through the second opening.

17. The method of claim **15**, wherein the air mover comprises a fan or a blower.

18. The method of claim **15**, wherein the shroud includes a first removable cover over the first opening and a second removable cover over the second opening, the method further comprising removing the first removable cover and moving air through the first opening or removing the second removable cover and moving air through the second opening.

19. The method of claim **18**, wherein the heat generating component is positioned in a first enclosure and the first removable cover is removed and air moved through the first opening and thereafter the second removable cover is removed and air is moved through the second opening.

20. The method of claim **18**, wherein the heat generating component is positioned in a second enclosure after the first enclosure and the second removable cover is removed and air moved through the second opening.

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